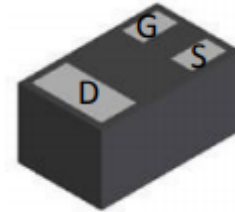
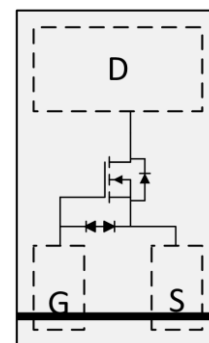


**WNM6012**
**Single N-Channel, 60V, 250mA, Power MOSFET**
<http://www.omnivision-group.com>

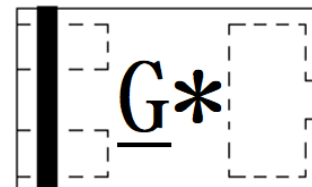
V <sub>DS</sub> (V)	Max R <sub>DS(on)</sub> (Ω)
60	7.5@ V <sub>GS</sub> =10V
	9.5@ V <sub>GS</sub> =4.5V
	24.0@ V <sub>GS</sub> =2.5V
ESD Rating: 2000V HBM	


**DFN1006-3L**
**Description**

The WNM6012 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM6012 is Pb-free.


**Features**

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package DFN1006-3L

**Pin configuration (Top view)**

G = Device Code

\* = Month(A~Z)

**Marking**
**Applications**

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

**Order information**

Device	Package	Shipping
WNM6012-3/TR	DFN1006-3L	10K/Tape&Reel

### Absolute Maximum ratings

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	$T_A=25^\circ\text{C}$	250
		$T_A=70^\circ\text{C}$	200
Pulsed Drain Current <sup>c</sup>	$I_{DM}$	500	mA
Maximum Power Dissipation <sup>b</sup>	$P_D$	$T_A=25^\circ\text{C}$	
		$T_A=70^\circ\text{C}$	645
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ\text{C}$

### Thermal resistance ratings

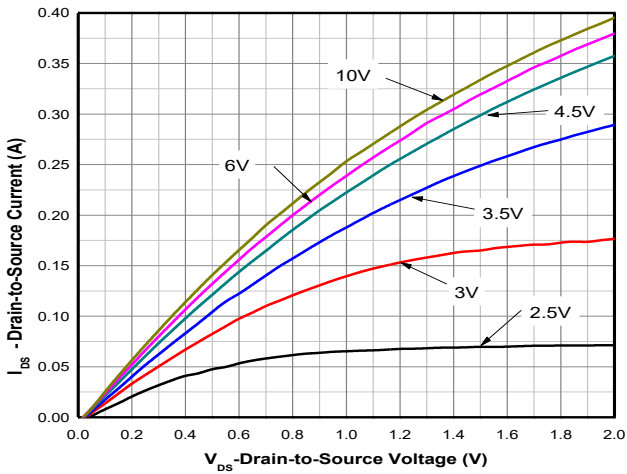
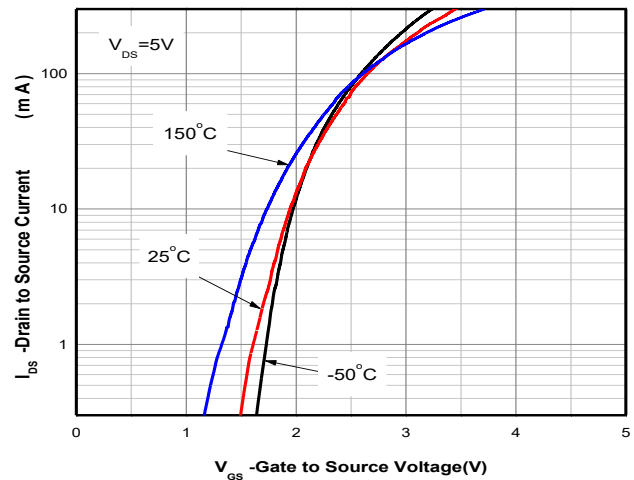
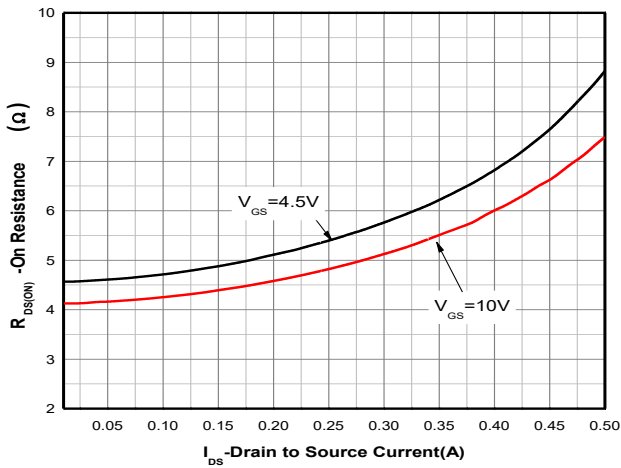
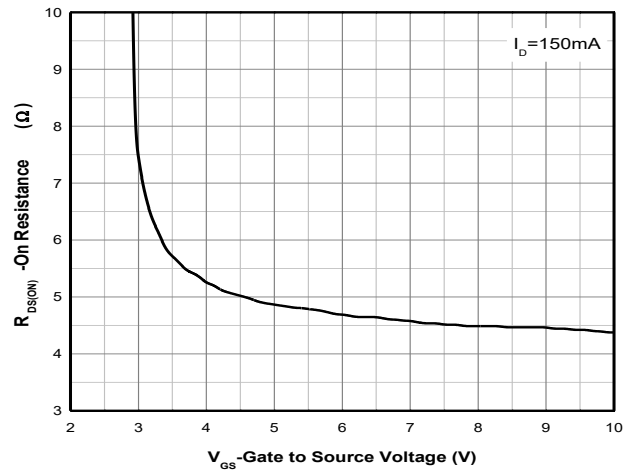
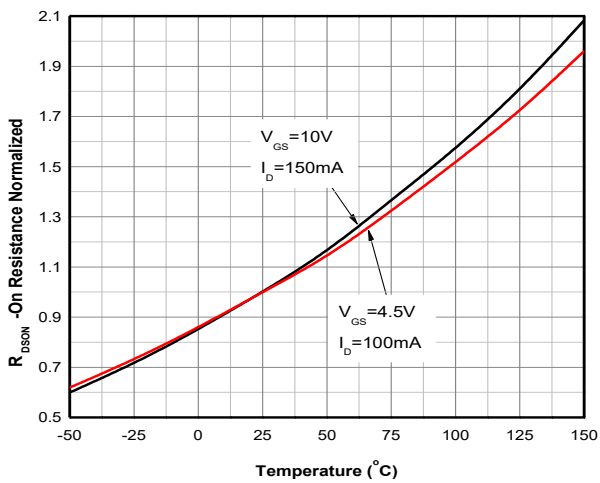
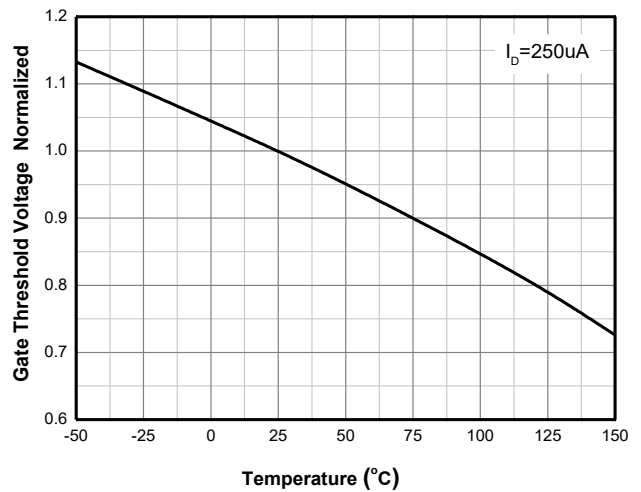
Single Operation				
Parameter		Symbol	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$t \leq 10 \text{ s}$	$R_{\theta JA}$	94	$^\circ\text{C/W}$
	Steady State		124	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	$t \leq 10 \text{ s}$	$R_{\theta JA}$	221	
	Steady State		299	

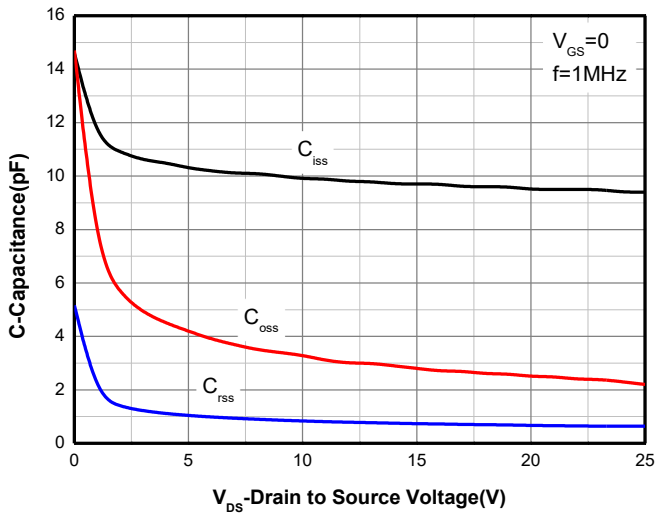
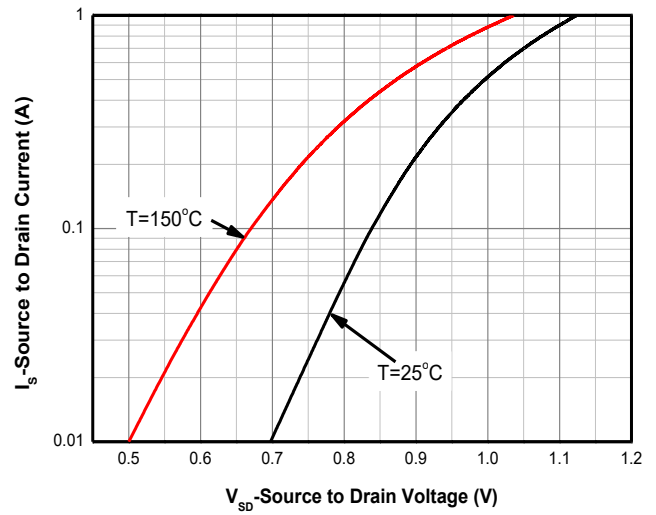
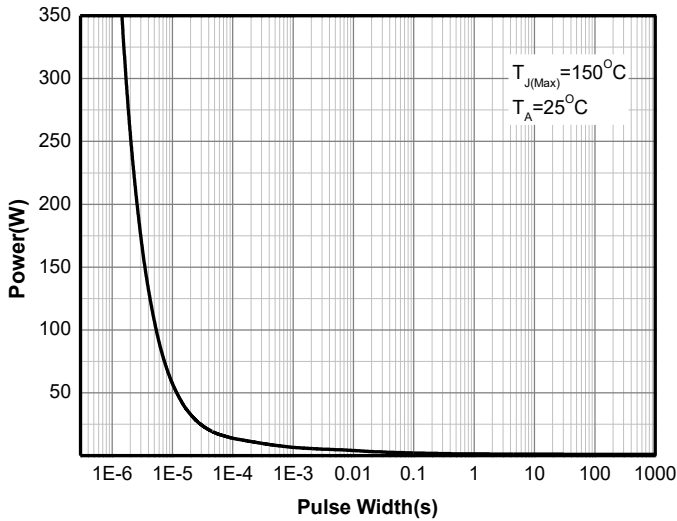
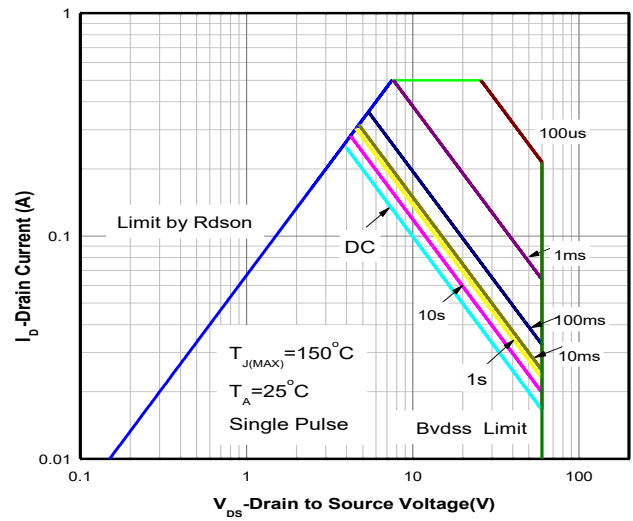
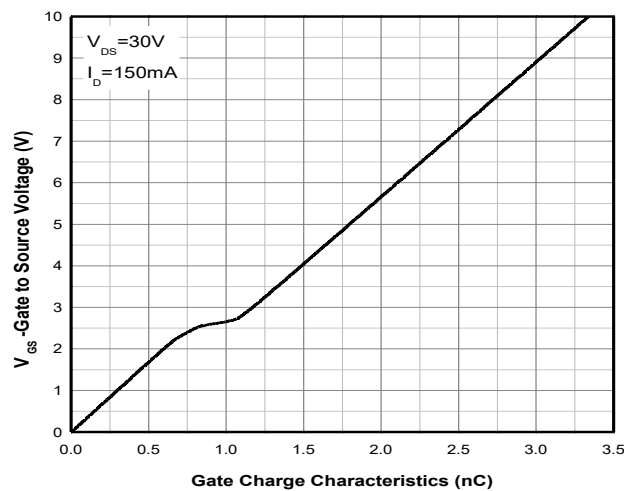
**Note:**

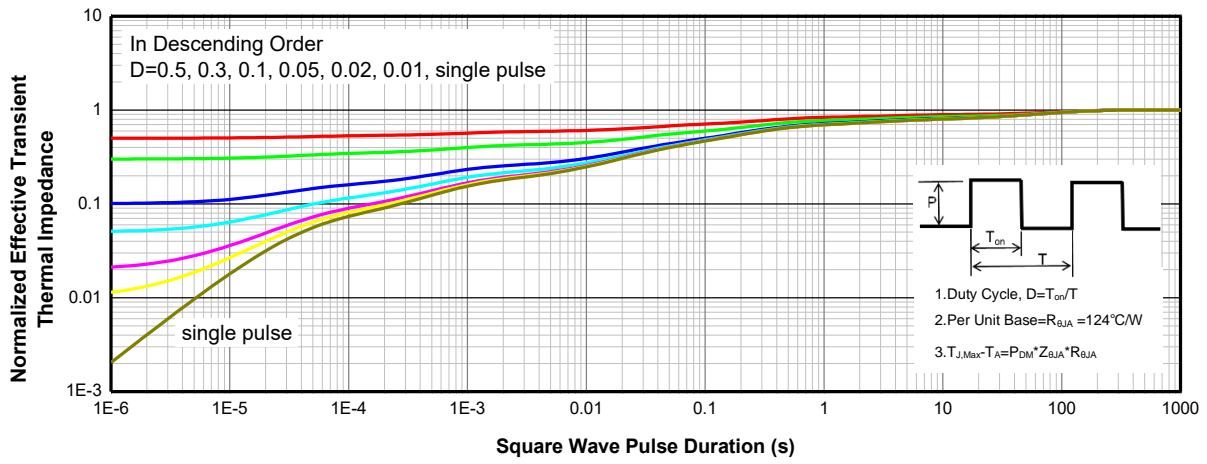
- a The value of  $R_{\theta JA}$  is measured with the device mounted on 1-inch<sup>2</sup> (6.45cm<sup>2</sup>) with 2oz.(0.071mm thick) Copper pad on a 1.5\*1.5 inch<sup>2</sup>, 0.06-inch thick FR4 PCB, in a still air environment with  $T_A = 25^\circ\text{C}$ . The power dissipation  $P_D$  is based on  $R_{\theta JA}$  value and the  $T_{J(MAX)}=150^\circ\text{C}$ . The value in any given application is determined by the user's specific board design, and the maximum temperature of  $150^\circ\text{C}$  may be used if the PCB allows it to.
- b The value of  $R_{\theta JA}$  is measured with the device mounted on FR-4 minimum pad board, in a still air environment with  $T_A = 25^\circ\text{C}$ . The power dissipation  $P_D$  is based on  $R_{\theta JA}$  value and the  $T_{J(MAX)}=150^\circ\text{C}$ . The value in any given application is determined by the user's specific board design, and the maximum temperature of  $150^\circ\text{C}$  may be used if the PCB allows it to.
- c Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial  $T_J = 25^\circ\text{C}$ , the maximum allowed junction temperature of  $150^\circ\text{C}$ .
- d The static characteristics are obtained using ~380us pulses, duty cycle ~1%.

**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

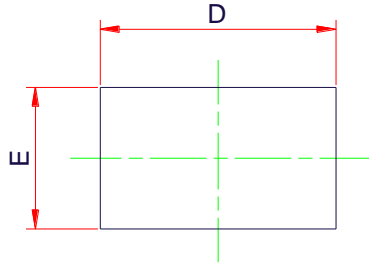
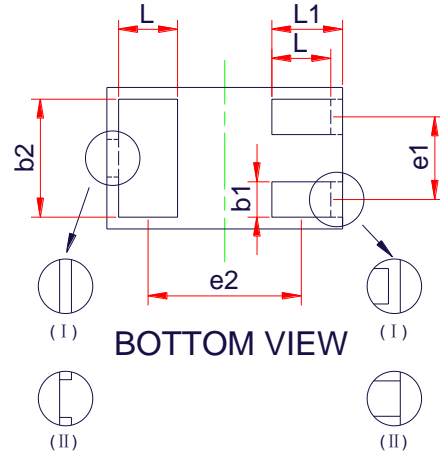
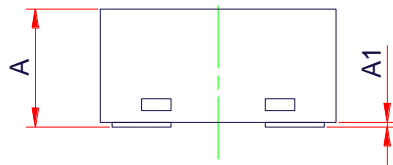
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250uA	60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V			1	uA
Gate-to-source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20V			±10	uA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250uA	1.0	1.5	2.3	V
Drain-to-source On-resistance <sup>d</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 150mA		4.4	7.5	Ω
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 100mA		4.7	9.5	
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 10mA		7.9	24.0	
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1.0MHz, V <sub>DS</sub> = 25 V		9.4		pF
Output Capacitance	C <sub>OSS</sub>			2.2		
Reverse Transfer Capacitance	C <sub>RSS</sub>			0.7		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 30V, I <sub>D</sub> = 150m A		3.4		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>			0.4		
Gate-to-Source Charge	Q <sub>GS</sub>			0.8		
Gate-to-Drain Charge	Q <sub>GD</sub>			0.3		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	t <sub>d(ON)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 30 V, I <sub>D</sub> = 150m A , R <sub>G</sub> = 10Ω		2.0		ns
Rise Time	t <sub>r</sub>			5.0		
Turn-Off Delay Time	t <sub>d(OFF)</sub>			6.8		
Fall Time	t <sub>f</sub>			60.0		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 200mA		0.9	1.2	V

**Typical Characteristics (Ta=25°C, unless otherwise noted)**

**Output Characteristics <sup>d</sup>**

**Transfer Characteristics <sup>d</sup>**

**On-Resistance vs. Drain Current <sup>d</sup>**

**On-Resistance vs. Gate-to-Source Voltage <sup>d</sup>**

**On-Resistance vs. Junction Temperature <sup>d</sup>**

**Threshold Voltage vs. Temperature**

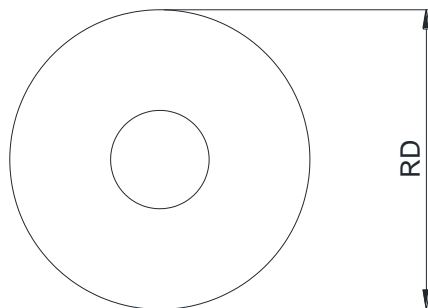
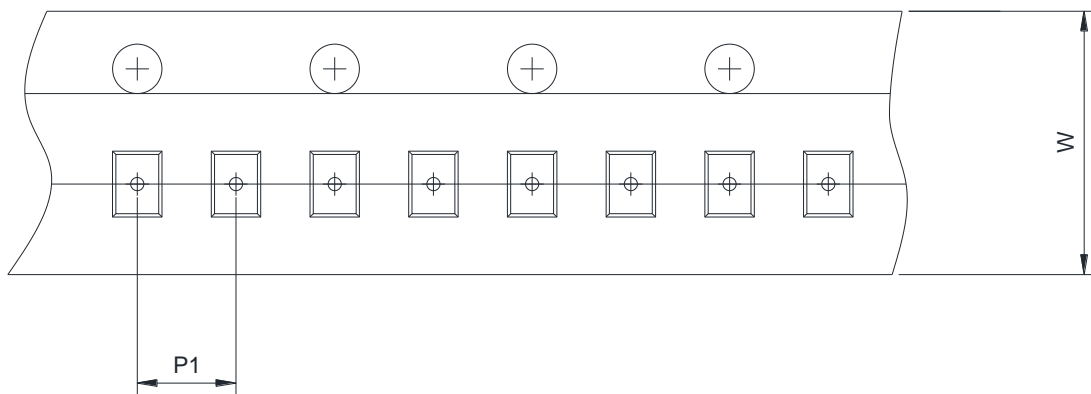
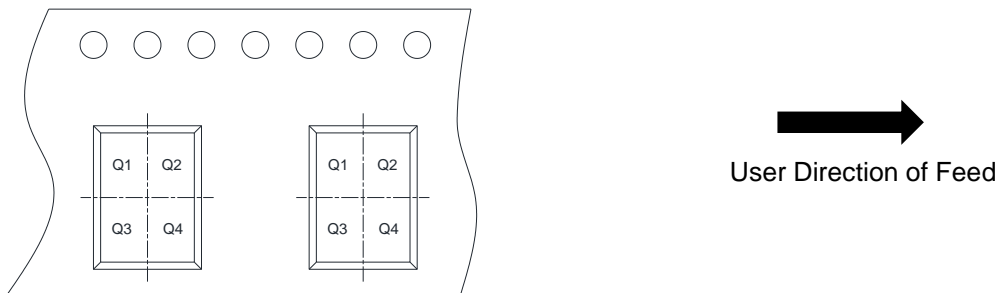

**Capacitance**

**Body Diode Forward Voltage**

**Single Pulse power**

**Safe Operating Power**

**Gate Charge Characteristics**



**Transient thermal response (Junction-to-Ambient)**

**PACKAGE OUTLINE DIMENSIONS**
**DFN1006-3L**

**TOP VIEW**

**BOTTOM VIEW**

**SIDE VIEW**

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.36	-	0.50
A1	0.00	-	0.05
D	0.95	1.00	1.05
E	0.55	0.60	0.65
b1	0.10	0.15	0.20
b2	0.40	0.50	0.60
L	0.20	0.25	0.30
L1	0.20	0.30	0.40
e1	0.35Ref		
e2	0.65 Ref		

**TAPE AND REEL INFORMATION**
**Reel Dimensions**

**Tape Dimensions**

**Quadrant Assignments For PIN1 Orientation In Tape**


RD	Reel Dimension	<input checked="" type="checkbox"/> 7inch	<input type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input checked="" type="checkbox"/> 8mm	<input type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input checked="" type="checkbox"/> 2mm	<input type="checkbox"/> 4mm <input type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input type="checkbox"/> Q1	<input type="checkbox"/> Q2 <input checked="" type="checkbox"/> Q3 <input checked="" type="checkbox"/> Q4



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